



ASSOCIATION CONNECTING  
ELECTRONICS INDUSTRIES®

### Material Composition Declaration

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This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.

1752-2 1.1

ICP Web Site for information on IPC-1752 Standard  
<http://www.ipc.org>

Form Type\*  
Distribute

Declaration Class\*  
Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg  
Information

#### Supplier Information

<b>Company Name *</b> Fairchild Semiconductor	Company Unique ID 00-489-5751	Unique ID Authority Dun & Bradstreet	<b>Response Date*</b> Jul 14, 2015
<b>Contact Name *</b> Jolene Small	Title - Contact Product Ecology	<b>Phone - Contact *</b> 207-761-6214	<b>Email - Contact *</b> jolene.small@fairchildsemi.com
<b>Authorized Representative *</b> Jolene Small	Title - Representative Product Ecology	<b>Phone - Representative *</b> 207-761-6214	<b>Email - Representative *</b> jolene.small@fairchildsemi.com


Requester Item Number	Mfr Item Number	Mfr Item Name	Effective Date	FSC Version	Manufacturing Site	Weight*	UOM	Unit Type
FFA60UP20DNTU	FFA60UP20DNTU	TO3PN-3	Jul 14, 2015	1.0	FSSZ	5.43465	g	Each

#### Manufacturing Process Information

Terminal Finish	Base Alloy	J-STD-020 MSL Rating	Peak Process Body Temperature	Max Time at Peak Temperature	No Reflow cycles
Sn	Copper Alloy	NA	Not Applicable		Not Applicable

\* Required Field

RoHS Material Composition Declaration		Declaration Type * Custom
<b>RoHS Directive</b> 2011/65/EU	<b>RoHS Definition:</b> Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium	
<p>This document is Fairchild Semiconductor's statement regarding the directive 2011/65/EU of the European Parliament and of the council of 8 June 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (RoHS Recast). The content of this document is based upon information collected from Fairchild Semiconductor supply chain, manufacturing facilities and affiliates worldwide.</p> <p>The FSC part number listed above and the homogenous materials in the product are compliant with the Directive 2011/65/EU. Fairchild has implemented systems to ensure our products are compliant to environmental regulations and laws worldwide. However, not all materials in Fairchild's products may have been independently verified regarding substance content. In the event of any issues arising from information in this document, the warranty section of Fairchild's standard terms and conditions of sale shall apply, unless alternate contracts have been agreed upon in writing by both parties.</p> <p>Note: The substance content disclosed herewith is approximate and is based on various methods including, engineering calculations, supplier surveys, Material Safety Data Sheets, analytical measurements. Fairchild may update this document without notification. This statement may not include information regarding the miniscule quantities of dopant and metal materials in the electrical devices contained within the finished product. CAS numbers listed for Resin substances are generic and may contain alternate substances of similar composition.</p>		
<b>RoHS Declaration *</b> <b>4 - Item(s) does not contain RoHS restricted substances per the definition above except for selected exemptions</b> <b>Supplier Acceptance * Accepted</b>		
<b>Exemptions:</b> If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.		
<p>Exemption List Version EL-2011/534/EU</p> <p>7(a) Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead).</p>		

Declaration Signature	
Supplier Signature	 JOLENE SMALL – PRODUCT ECOLOGY ENGINEER

**Homogeneous Material Composition Declaration for Electronic Products**

Item/SubItem Name TO3PN-3.csv

Component	Material	Weight (mg)	Jig Level	Substance Category	Substance	Weight (mg)	CAS	PPM	
Chip	Other inorganic materials	41.8	Supplier		Silicon	41.8	7440-21-3	7691	
Die Attach	Other Nonferrous metals & alloys	1.84	A	Lead/Lead Compounds	Lead	1.72	7439-92-1	317	
			Supplier		Silver	0.028	7440-22-4	5	
			Supplier		Tin	0.092	7440-31-5	17	
Encapsulation	Thermoplastics	1736.8	B	Antimony/Antimony Compounds	Antimony Trioxide	43.5	1309-64-4	8004	
			B		Brominated Flame Retardants (other than PBCs or PBDEs)	Bromine Resin	52.2	6386-73-8	9605
			Supplier			Carbon Black	13.1	1333-86-4	2410
			Supplier			Epoxy Resin	348	29690-82-2	64034
			Supplier			Silica, vitreous	1280	60676-86-0	235526
Lead Frame	Copper & its alloys	3624.71	Supplier	Copper		3620	7440-50-8	666096	
Supplier			Phosphorus	1.09	7723-14-0	201			
Supplier			Tin	3.62	7440-31-5	666			
Plating	Other Nonferrous metals & alloys	26.5	Supplier		Tin	26.5	7440-31-5	4876	
Wire Bond	Aluminum & its alloys	3	Supplier		Aluminum	3	7429-90-5	552	